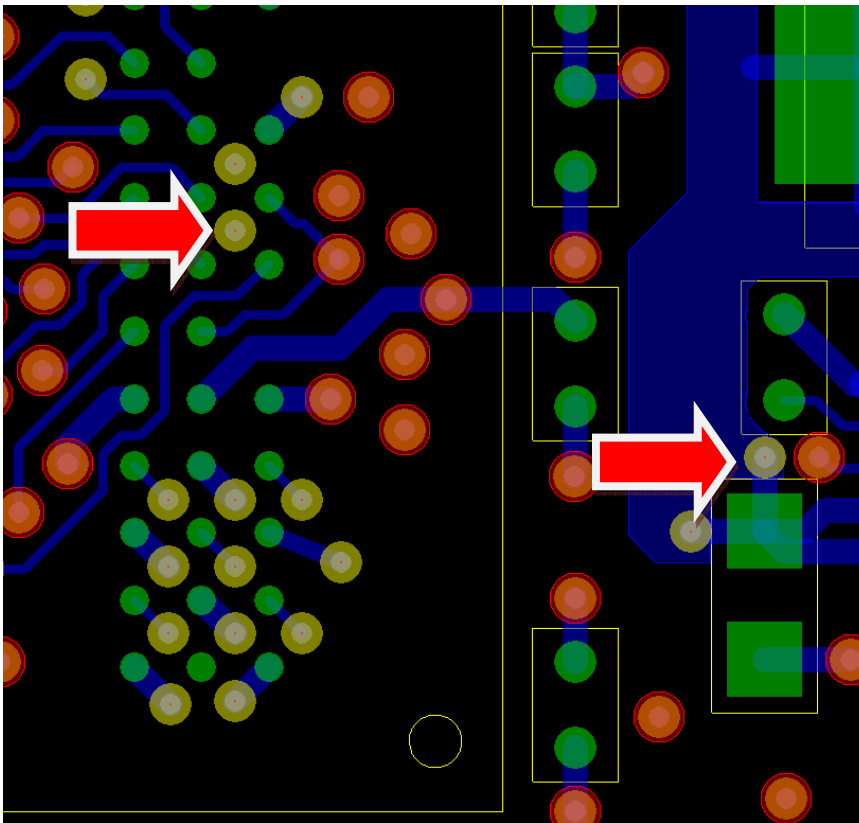
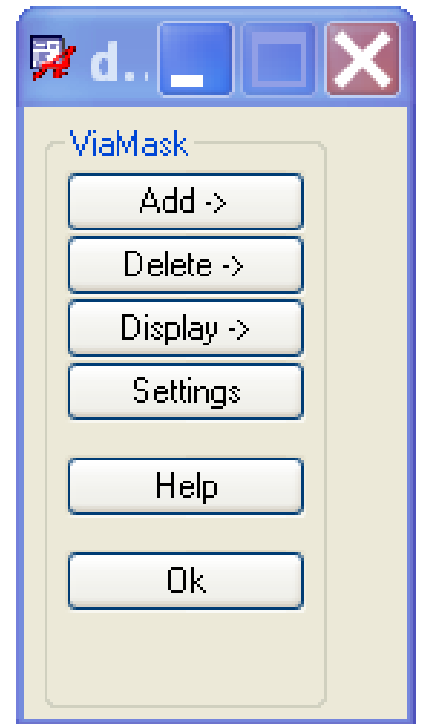


## ViaMask

Automatically modifies via soldermask openings that are less than a specified distance to solder paste pads.

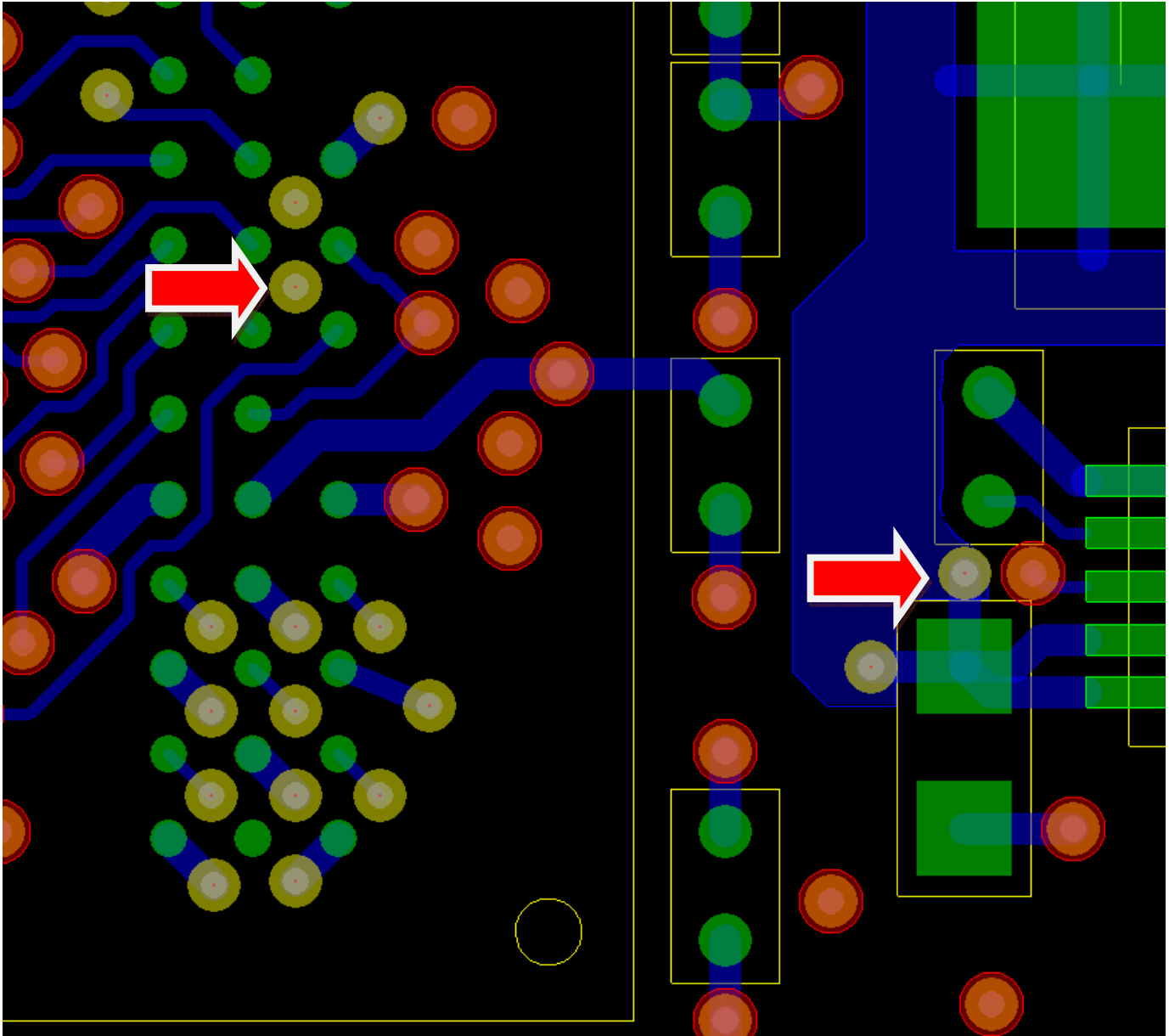
Features:

- Helps prevent assembly process solder bridges between smt pads and vias.
- Drc mode flags missing or incorrect openings.
- Add via soldermask modifications by selection.
- Much faster and less error prone than changing individual via padstacks manually.



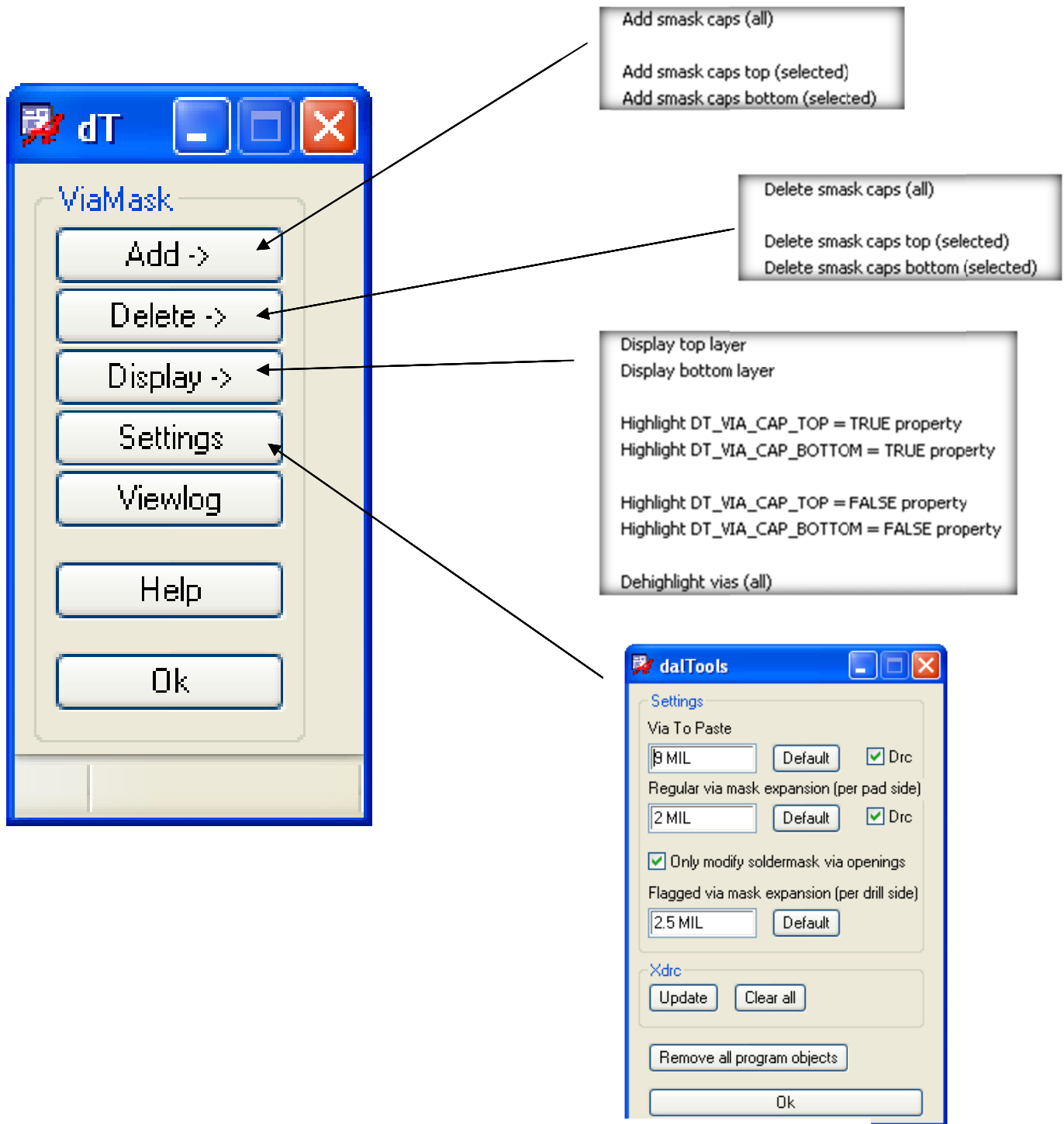
## Example

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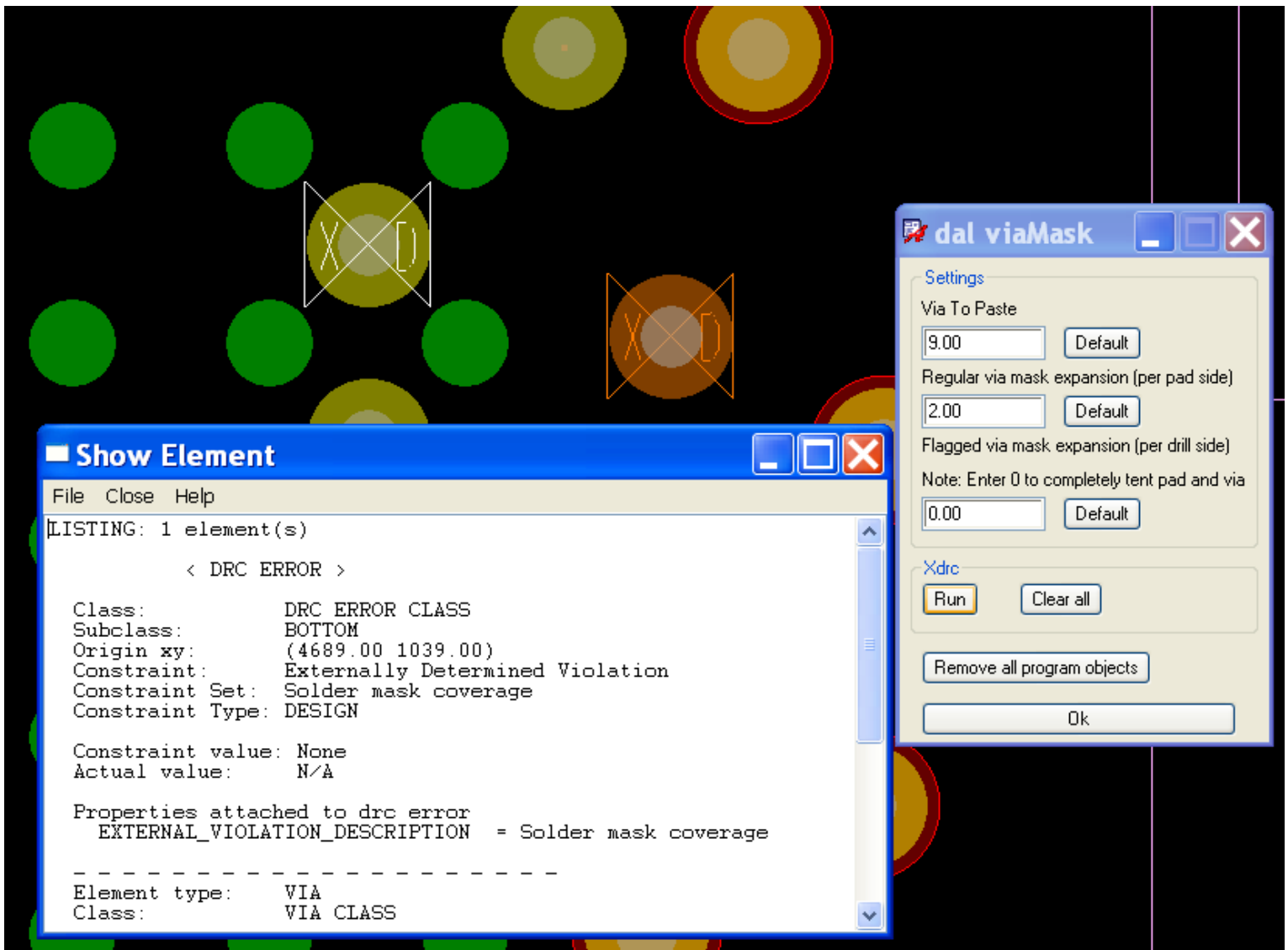


Vias are (Yellow). Pins are (Green). Notice how the soldermask openings (Red) are automatically reduced when they are close to a smt pad.

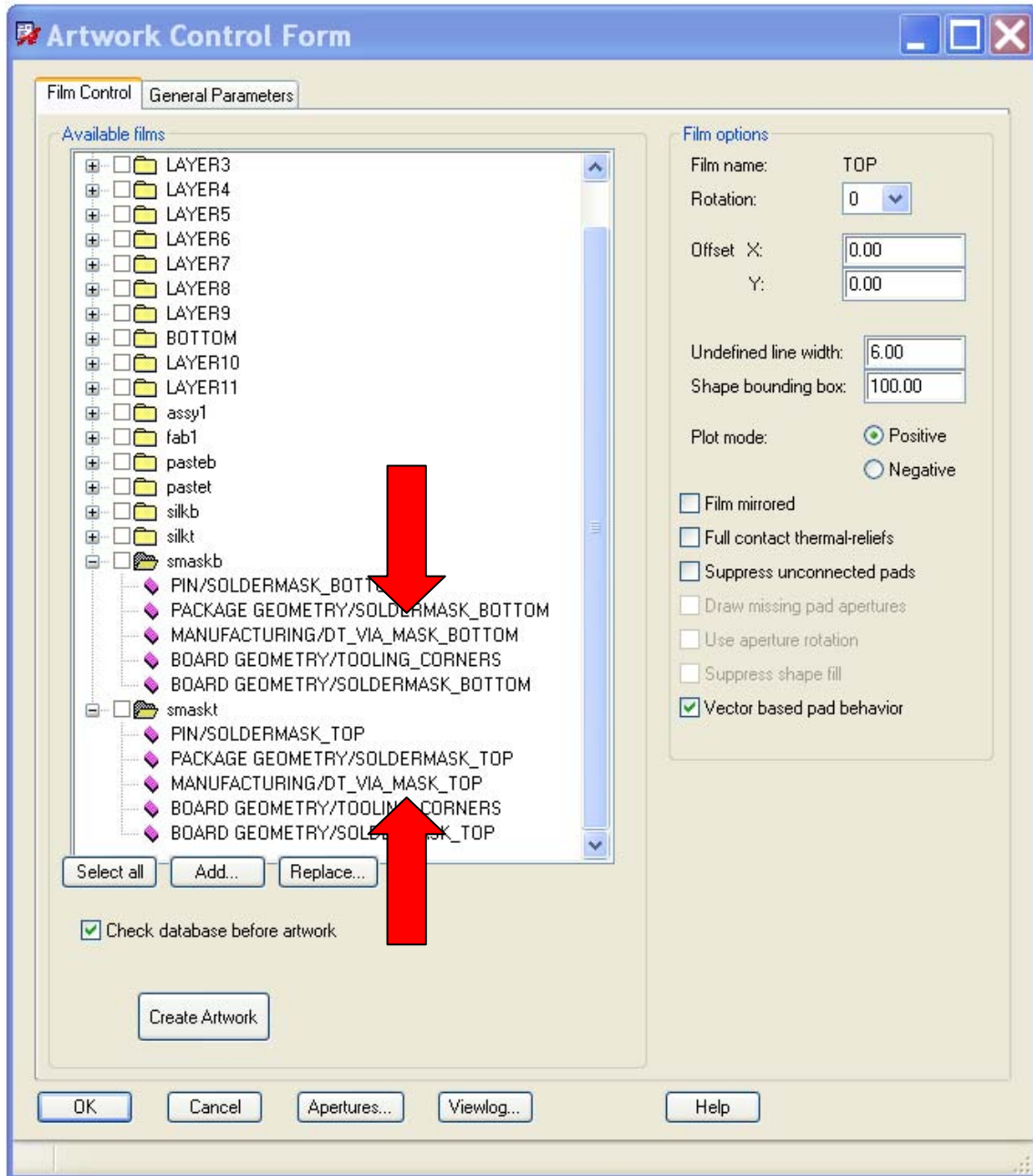
# Features



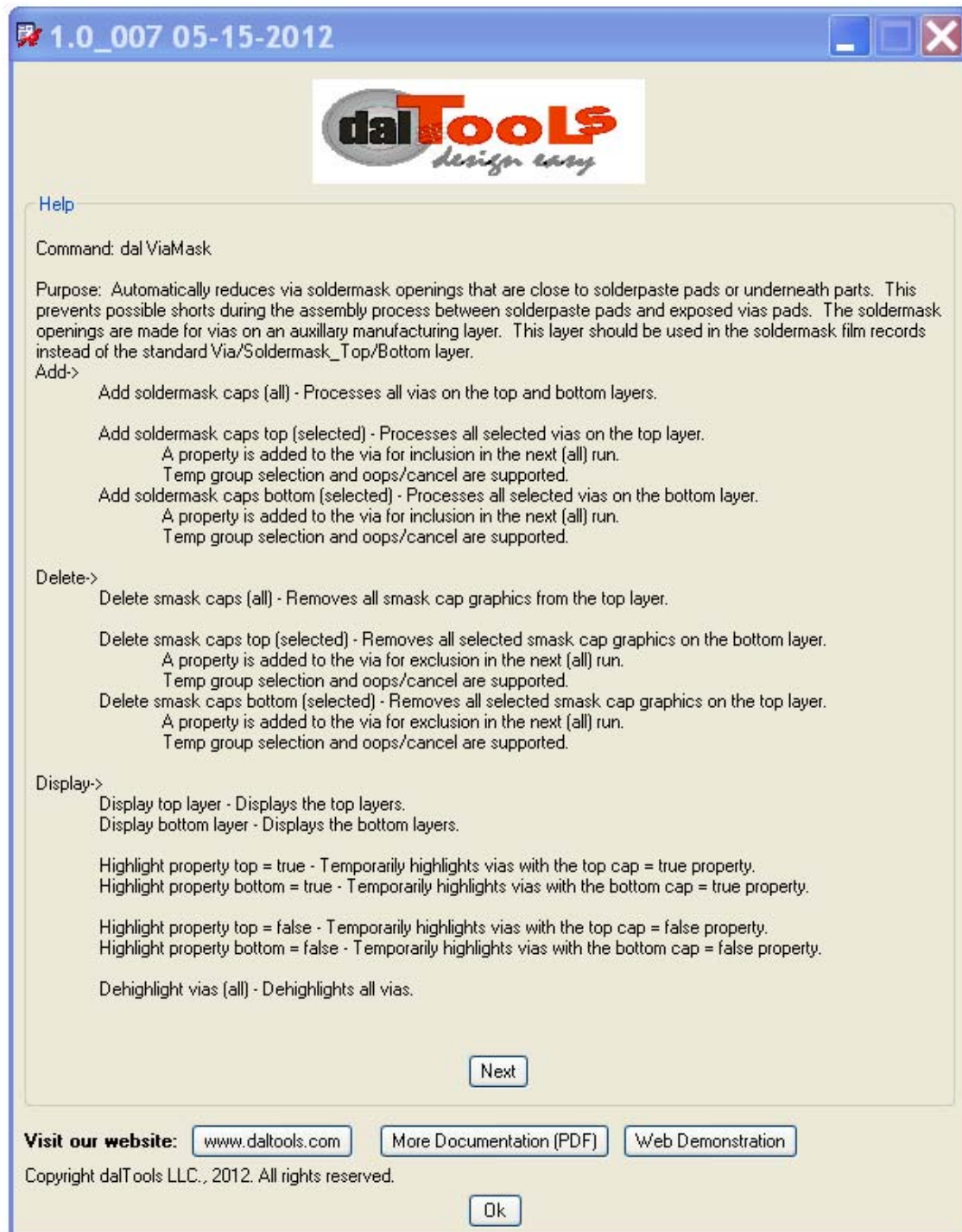
## DRC checks for missing or incorrect openings




# Artwork Control Form (continued)



# Help



1.0\_007 05-15-2012



## Help

Command: dal ViaMask

Purpose: Automatically reduces via soldermask openings that are close to solderpaste pads or underneath parts. This prevents possible shorts during the assembly process between solderpaste pads and exposed vias pads. The soldermask openings are made for vias on an auxiliary manufacturing layer. This layer should be used in the soldermask film records instead of the standard Via/Soldermask\_Top/Bottom layer.

Add->

- Add soldermask caps (all) - Processes all vias on the top and bottom layers.
- Add soldermask caps top (selected) - Processes all selected vias on the top layer.  
A property is added to the via for inclusion in the next (all) run.  
Temp group selection and oops/cancel are supported.
- Add soldermask caps bottom (selected) - Processes all selected vias on the bottom layer.  
A property is added to the via for inclusion in the next (all) run.  
Temp group selection and oops/cancel are supported.

Delete->

- Delete smask caps (all) - Removes all smask cap graphics from the top layer.
- Delete smask caps top (selected) - Removes all selected smask cap graphics on the bottom layer.  
A property is added to the via for exclusion in the next (all) run.  
Temp group selection and oops/cancel are supported.
- Delete smask caps bottom (selected) - Removes all selected smask cap graphics on the top layer.  
A property is added to the via for exclusion in the next (all) run.  
Temp group selection and oops/cancel are supported.

Display->

- Display top layer - Displays the top layers.
- Display bottom layer - Displays the bottom layers.
- Highlight property top = true - Temporarily highlights vias with the top cap = true property.
- Highlight property bottom = true - Temporarily highlights vias with the bottom cap = true property.
- Highlight property top = false - Temporarily highlights vias with the top cap = false property.
- Highlight property bottom = false - Temporarily highlights vias with the bottom cap = false property.
- Dehighlight vias (all) - Dehighlights all vias.

Next

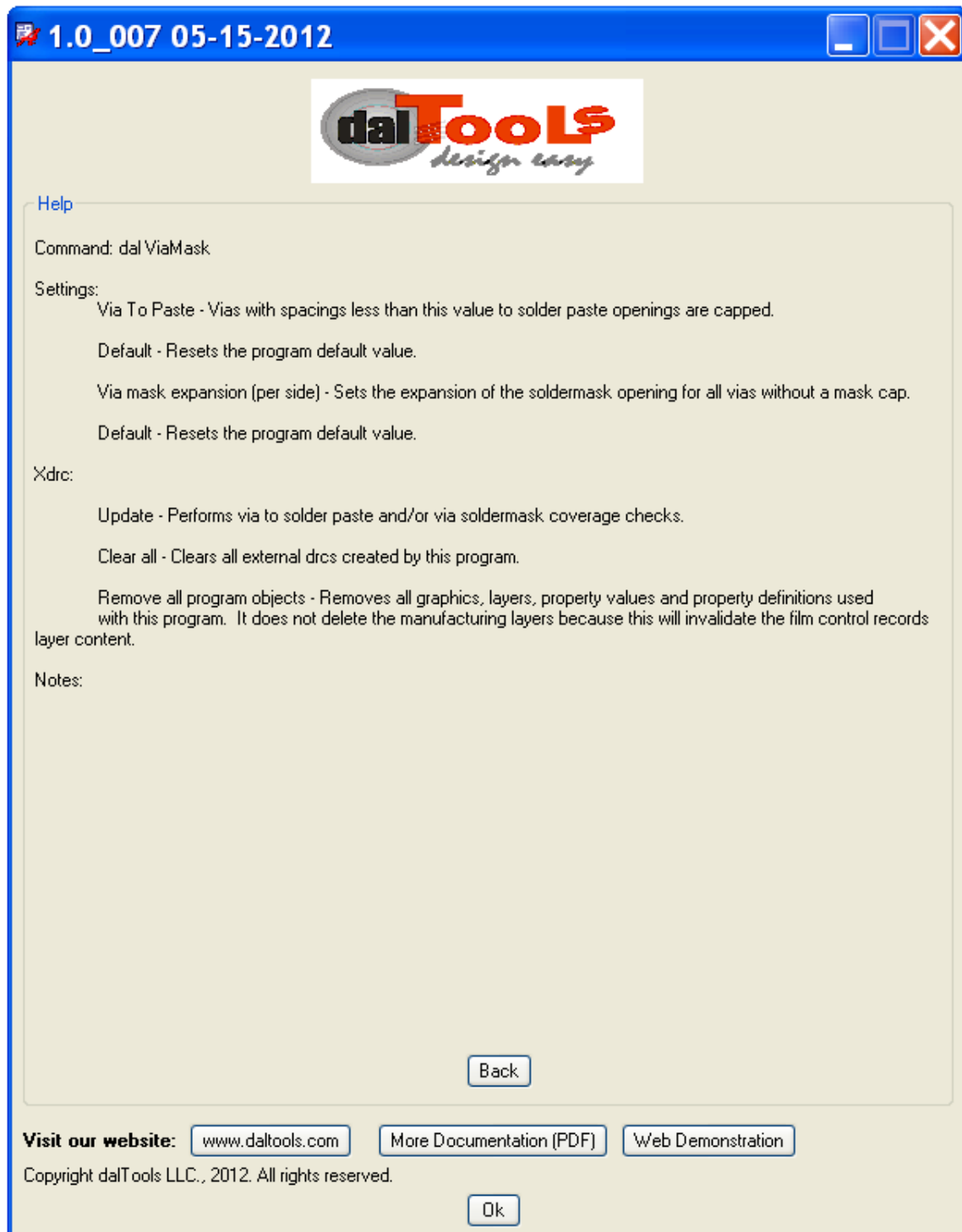
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Ok

## Help (continued)

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**Help**

Command: dal ViaMask

Settings:

- Via To Paste - Vias with spacings less than this value to solder paste openings are capped.
- Default - Resets the program default value.
- Via mask expansion (per side) - Sets the expansion of the soldermask opening for all vias without a mask cap.
- Default - Resets the program default value.

Xdrc:

- Update - Performs via to solder paste and/or via soldermask coverage checks.
- Clear all - Clears all external drcs created by this program.
- Remove all program objects - Removes all graphics, layers, property values and property definitions used with this program. It does not delete the manufacturing layers because this will invalidate the film control records layer content.

Notes:

Back

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Ok